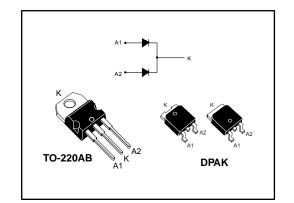


STPS20LCD200C

High voltage power Schottky rectifier

Datasheet - production data



Features

- High junction temperature capability
- Good trade-off between leakage current and forward voltage drop
- Low leakage current
- ECOPACK[®]2 compliant component for DPAK on demand

Description

This dual diode Schottky rectifier is suitable for high frequency switched mode power supplies.

Packaged in DPAK and TO-220AB, this device is intended to be used in SMPS TV, providing these applications with a good efficiency at both low and high load.

Table 1: Device	summary
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Symbol	Value
I _{F(AV)}	2 x 10 A
VRRM	200 V
V⊧ (typ.)	0.76 V
T _j (max.)	175 °C

September 2017

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This is information on a product in full production.

1 Characteristics

Table 2: Absolute ratings (limiting values per diode at T_{amb} = 25 °C unless otherwise specified)

Symbol	Paramete	Value	Unit			
Vrrm	Repetitive peak reverse voltage			200	V	
I _{F(RMS)}	Forward rms current	20	А			
1	Average forward current $\delta = 0.5$,		Per diode	10	^	
IF(AV)	square wave (DPAK, TO-220AB)	T _c = 140 °C	Per device	20	A	
	I _{FSM} Surge non repetitive forward current t _p = sin		DPAK	125	•	
IFSM			TO-220AB	150	A	
T _{stg}	Storage temperature range	-65 to +175	°C			
Tj	Maximum operating junction temperature ⁽¹⁾				°C	

Notes:

 $^{(1)}(dP_{tot}/dT_j) < (1/R_{th(j-a)})$ condition to avoid thermal runaway for a diode on its own heatsink.

Symbol	Parameter	Value	Unit	
Dens	lunction to coop	Per diode	3	
R _{th(j-c)}	Junction to case	Total	1.8	°C/W
Rth(c)	Coupling		0.6	

Table 3: Thermal resistance parameters

When the two diodes 1 and 2 are used simultaneously:

 ΔT_j (diode1) = P(diode1) x R_{th(j-c)}(per diode) + P(diode2) x R_{th(c)}

Symbol	Parameter	Test conditions		Min.	Тур.	Max.	Unit
	Povorao lookago ourront	T _j = 25 °C	V _R = V _{RRM}	-		5	μA
IR	I _R ⁽¹⁾ Reverse leakage current	T _j = 125 °C	VR – VRRM	-	0.7	2.5	mA
		T _j = 25 °C	I _F = 10 A	-		0.95	
V _F ⁽²⁾		T _j = 125 °C	I⊧ = 10 A	-	0.76	0.81	V
V _F ⁽²⁾ Forward voltage drop	Tj = 25 °C	I _F = 20 A	-		1.125	V	
			T _j = 125 °C	-	0.89	0.97	

Notes:

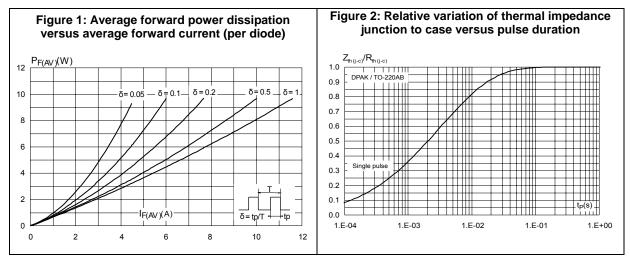
$$\label{eq:powerset} \begin{split} ^{(1)} \mbox{Pulse test: } t_{\mbox{p}} = 5 \mbox{ ms, } \delta < 2\% \\ ^{(2)} \mbox{Pulse test: } t_{\mbox{p}} = 380 \mbox{ µs, } \delta < 2\% \end{split}$$

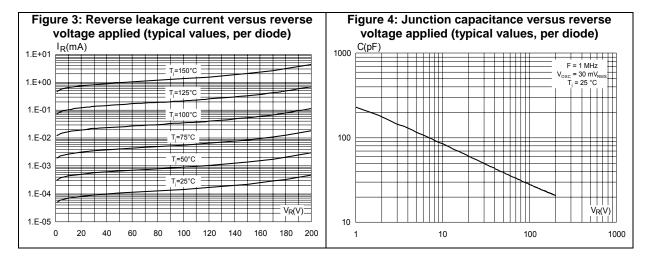
To evaluate the conduction losses use the following equation:

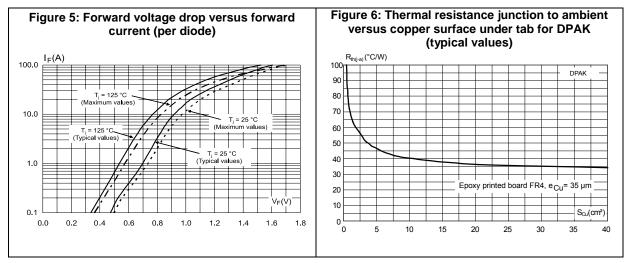
 $P = 0.65 \text{ x } I_{F(AV)} + 0.016 \text{ x } I_{F^2(RMS)}$



1.1 Characteristics (curves)







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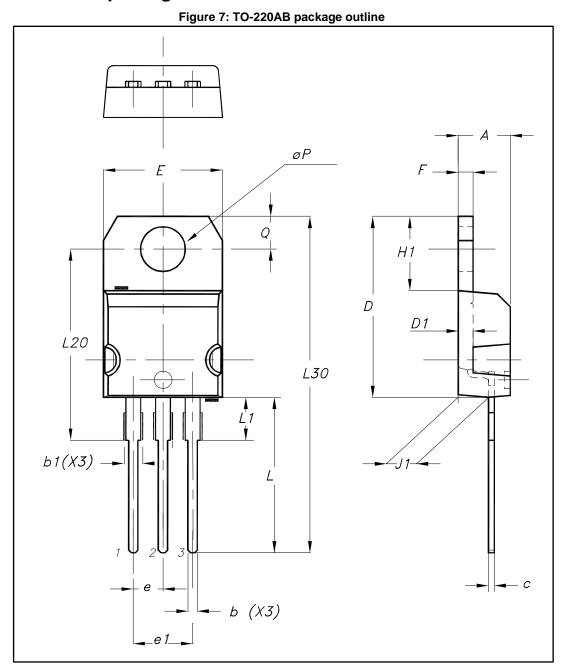
2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: *www.st.com*. ECOPACK[®] is an ST trademark.

- Cooling method: by conduction (C)
- Epoxy meets UL 94,V0
- Recommended torque value: 0.55 N·m (for TO-220AB)
- Maximum torque value: 0.7 N·m (for TO-220AB)



2.1 TO-220AB package information





Package information

STPS20LCD200C

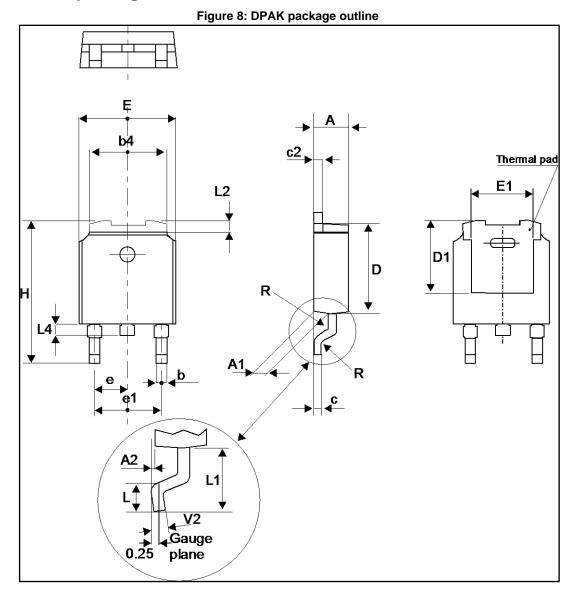
	Table 5: TO-220AB package mechanical data				
		ensions			
Ref.	Millin	Millimeters		hes	
	Min.	Max.	Min.	Max.	
A	4.40	4.60	0.173	0.181	
b	0.61	0.88	0.240	0.035	
b1	1.14	1.70	0.045	0.067	
С	0.48	0.70	0.019	0.028	
D	15.25	15.75	0.600	0.620	
D1	1.27	typ.	0.050) typ.	
E	10.00	10.40	0.394	0.409	
е	2.40	2.70	0.094	0.106	
e1	4.95	5.15	0.195	0.203	
F	1.23	1.32	0.048	0.052	
H1	6.20	6.60	0.244	0.260	
J1	2.40	2.72	0.094	0.107	
L	13.00	14.00	0.512	0.551	
L1	3.50	3.93	0.138	0.155	
L20	16.40 typ.		0.646 typ.		
L30	28.9	D typ.	1.138	3 typ.	
θΡ	3.75	3.85	0.148	0.152	
Q	2.65	2.95	0.104	0.116	

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2.2 DPAK package information



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This package drawing may slightly differ from the physical package. However, all the specified dimensions are guaranteed.

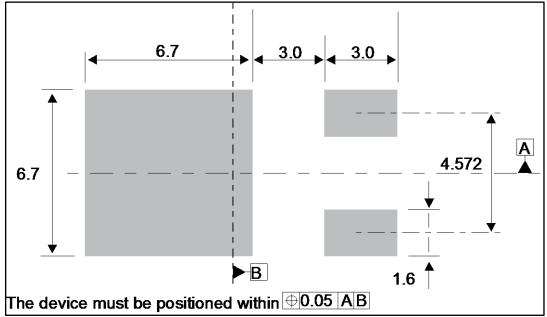


Package information

STPS20LCD200C

Table 6: DPAK package mechanical data				
Dimensions				
Ref.	Mill	Millimeters		hes
	Min.	Max.	Min.	Max.
А	2.18	2.40	0.085	0.094
A1	0.90	1.10	0.035	0.043
A2	0.03	0.23	0.001	0.009
b	0.64	0.90	0.025	0.035
b4	4.95	5.46	0.194	0.215
с	0.46	0.61	0.018	0.024
c2	0.46	0.60	0.018	0.023
D	5.97	6.22	0.235	0.244
D1	4.95	5.60	0.194	0.220
E	6.35	6.73	0.250	0.265
E1	4.32	5.50	0.170	0.216
е	2.2	86 typ.	0.090) typ.
e1	4.40	4.70	0.173	0.185
Н	9.35	10.40	0.368	0.409
L	1.0	1.78	0.039	0.070
L2		1.27		0.050
L4	0.60	1.02	0.023	0.040
V2	-8°	+8°	-8°	+8°

Figure 9: DPAK recommended footprint (dimensions in mm)



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3 Ordering information

Table 7: Ordering information					
Order code Marking Package Weight Base qty. Delivery				Delivery mode	
STPS20LCD200CBTR	S20LCD200C	DPAK	0.32 g	2500	Tape and reel
STPS20LCD200CT	STPS20LCD200C	TO-220AB	1.95 g	50	Tube

4 Revision history

Table 8: Document revision history

Date	Revision	Changes
09-Aug-2013	1	First issue
27-Sep-2013	2	Updated Figure 9 and Table 5.
18-Dec-2015	3	Updated DPAK package information and reformatted to current standard.
22-Sep-2017	4	Removed TO-220FPAB package.



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